



Material Content Data Sheet



Sales Product Name		TLE94108EL		Issued		20. July 2018			
MA#		MA001658658							
Package		PG-SSOP-24-9		Weight*		150.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.240	2.15	2.15	21480	21480	
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111		
	non noble metal	zinc	7440-66-6	0.067	0.04		446		
	non noble metal	iron	7439-89-6	1.345	0.89		8917		
wire	non noble metal	copper	7440-50-8	54.617	36.21	37.15	362087	371561	
	non noble metal	copper	7440-50-8	0.853	0.57	0.57	5657	5657	
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1148	
encapsulation	plastics	epoxy resin	-	7.965	5.28		52806		
	inorganic material	silicondioxide	60676-86-0	78.440	52.00	57.39	520025	573979	
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19298	19298	
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553	
glue	plastics	epoxy resin	-	0.244	0.16		1618		
	noble metal	silver	7440-22-4	0.732	0.49	0.65	4854	6472	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com